



# Information and Control Korea TC Chapter

## Meeting Summary and Minutes

Korea Standards Winter Meetings

Thursday, November 27, 2025

3:00 PM – 5:00 PM (KST)

SEMI Korea office, Seoul / OVTCCM (hybrid)

### TC Chapter Announcements

*Next TC Chapter Meeting*

April 23, 2026, OVTCCM.

### Table 1 Meeting Attendees

*Italics indicate virtual participants*

**Co-Chairs:** Chulhong Ahn (SK hynix), Hyungsu Kim (Doople), Kelvin Lee (Lam Research)

**SEMI Staff:** Natalie Shim, Cindy Bae (SEMI)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
ASM	Jung	IlGun	SCREEN	Nishimura	Takayuki
ASM	Kim	Gwanwoo	SEMI China	Ma	Sara
Doople	Kim	Hyungsu	SEMI Korea	Bae	Cindy
KCTech	Shim	Jongsub	SEMI Korea	Shim	Natalie
<i>Kokusai Electric</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>	SK hynix	Ahn	Chulhong
<i>KSIA</i>	<i>Seong</i>	<i>Jihye</i>	<i>Tata Electronics</i>	<i>Park</i>	<i>Jaeyong</i>
Linkgenesis	Chung	MinGyu	Tokyo Electron	Im	ByoungMin
Miracom	Lim	Youngshin	<i>Wonik IPS</i>	<i>Jung</i>	<i>JiKook</i>
PDF Solutions	Ryu	Ian	<i>Wonik IPS</i>	<i>Kim</i>	<i>Sehoon</i>
Samsung Electronics	Choi	Jinhyeok	<i>Wonik IPS</i>	<i>Park</i>	<i>Jungjin</i>
Samsung Electronics	Park	Young-chul			

### Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

### Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	



**Table 4 Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 5 Ratification Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&amp;R Action</i>	<i>A&amp;R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 6 Activities Approved by the GCS between meetings of the TC Chapter**

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

**Table 7 Authorized Activities**

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

**Table 8 Authorized Ballots**

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
None			

**Table 9 SNARF(s) Granted a One-Year Extension**

<i>#</i>	<i>TF</i>	<i>Title</i>	<i>Expiration Date</i>
None			

**Table 10 SNARF(s) Cancelled**

<i>#</i>	<i>TF</i>	<i>Title</i>
None		

**Table 11 Standard(s) to receive Inactive Status**

<i>Standard Designation</i>	<i>Title</i>
None	

**Table 12 New Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
2025-1127-1	SEMI Korea	Share the information regarding SEMI Traceability Phase 0 Activity with the Korea TC Members

**Table 13 Previous Meeting Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
None		

## 1 Welcome, Reminders, and Introductions

Chulhong Ahn (SK hynix) called the meeting to order at 3 PM. The meeting reminders on antitrust issues, intellectual property issues, and holding meetings with international attendance were reviewed. Attendees introduced themselves.

**Attachment:** 1. Required Meeting Elements March 2024  
2. Agenda\_I&C TC\_November27\_2025

## 2 Review of Previous Meeting Minutes

**Motion:** Approve the minutes with correction  
**By / 2<sup>nd</sup>:** Ian Ryu (PDF Solutions) / MinGyu Chung (Linkgenesis)  
**Discussion:** None  
**Vote:** 12-Y 0-N. Motion passed.

**Attachment:** 3. I&C TC Meeting Minutes\_July 18\_2025\_v2

## 3 Liaison Reports

### 3.1 I&C China TC Chapter

Sara Ma (SEMI China) reported for the I&C China TC Chapter. Of note:

#### 3.1.1 Meeting Information

- Last Meeting: April 8, Hybrid
- Next Meeting: Date to be decided

#### 3.1.2 Ballot Results

- Doc. 7139 — Line Item Revisions to E40-1218, Standard for Processing Management and E40.1-1218, Specification for SECS-II Protocol for Processing Management — **passed** with a technical change.
- Doc. 7140 — Line Item Revisions to E94-0819R, Specification for Control Job Management and E94.1-0819R, Specification for SECS-II Protocol for Control Job Management (CJM) — **passed** with a technical change.

3.1.3 Please find the attached file for details of TF activities.

**Attachment:** 4. China I&C Committee Chapter Liaison Report - Nov. 2025 v1



### 3.2 I&C Japan TC Chapter

Mitsuhiro Matsuda (Kokusai Electric) reported for the I&C Japan TC Chapter. Of note:

#### 3.2.1 Meeting Information

- Last Meeting: October 21, SEMI Japan Office / OVTCCM (hybrid)
- Next Meeting: December 19, TFT Building in conjunction with SEMICON Japan / OVTCCM (hybrid)

#### 3.2.2 Ballot Results

3.2.2.1 Doc. 7334 — Line Item Revision to SEMI E174-0819, Specification for Wafer Job Management — **passed** as balloted.

3.2.2.2 Doc. 7354 — Line Item Revision to SEMI E170-0520, Specification for Secured Foundation of Recipe Management System (Sforms) and SEMI E170.1-0520, Specification for SECS-II Protocol for Secured Foundation of Recipe Management System — 3 line items (LI-1, LI-3, LI-4) **passed** as balloted and 1 line item (LI-2) **passed** with technical changes.

#### 3.2.3 Authorized Activities

- The revision to the charter and scope section of the TFOF for Fab & Equipment Information Security TF has been authorized.

#### 3.2.4 Authorized Ballots

- None

3.2.5 Please find the attached file for details of TF activities.

**Attachment:** 5. JA\_I&C\_Liaison\_2025\_Nov\_rev1

### 3.3 North America TC Chapter

Natalie Shim (SEMI Korea) reported for the North America TC Chapter. Of note:

#### 3.3.1 Meeting Information

- Last Meeting: October 8, 2025
- Next Meeting: Date to be decided

#### 3.3.2 Leadership Changes

3.3.2.1 Digital Twins TF has been newly established.

- James Moyne (Applied Materials / University of Michigan), Brian Rubow (PDF Solutions), Chris Maloney (Intel), Fahad Golra (Agileo Automation) were appointed as co-leaders.

3.3.2.2 Sensor Bus TF is now dormant.

- Dan Judd (Arlington Laboratory) stepped down from the leader.

#### 3.3.3 Ballot Results

- Doc. 6743C — Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment — **passed**, and ratification ballot is to be issued.
- Doc. 7178A — Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata — **failed**.

Doc. 7321B — Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-0923 Specification for Equipment Self Description (EqSD), SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-0624 Specification for Protocol Buffers for



Equipment Client Authentication And Authorization (ECA), SEMI E134-0624 Specification for Data Collection Management, SEMI E134.2-0624 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-0624 Specification for Protocol Buffers Common Components — 1 line item (LI-1) **passed** and 1 line item (LI-2) **passed** with editorial changes.

- Doc. 7344 — Line Item Revision to SEMI E192-0121 - Guide for Equipment Adoption Criteria for GEM and GEM-Related Standards — 1 line item (LI-1) **failed**.
- Doc. 7345 — Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking — 1 line item (LI-1) **failed**.
- Doc. 7346 — Line Item Revision to SEMI E54.23-0520, Specification for Sensor/Actuator Network Communications for CC-Link®IE — 2 line items (LI-1, LI-2) **passed** as balloted.
- Doc. 7376 — Line Item Revision to SEMI E30-0125 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM), SEMI E30.1-0217 (Reapproved 0423) Specification for Inspection and Review Specific Equipment Model (ISEM) — 1 line item (LI-1) **passed** as balloted.
- Doc. 7377 — Line Item Revision to SEMI E40-0324 - Specification for Processing Management and SEMI E40.1-1218 (0324) Specification for SECS-II Protocol for Processing Management — 1 line item (LI-1) **passed** as balloted.
- Doc. 7378 — Line Item Revision to SEMI E87-0225 - Specification for Carrier Management (CMS) and SEMI E87.1-0225 - Specification for SECS-II Protocol for Carrier Management (CMS) — 2 line items (LI-1, LI-2) **passed** as balloted.
- Doc. 7380 — Line Item Revision to SEMI E142-0225 - Specification for Substrate Mapping, SEMI E142.1-0225 — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 (0225) — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 (0225) — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer — 1 line item (LI-1) **failed** and 1 line item (LI-2) **passed** with editorial changes.
- Doc. 7382 — Reapproval of SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC) **failed**.

### 3.3.4 Activities Authorized by GCS between Meetings

#### 3.3.4.1 2 SNARFS were approved.

- Doc. 7357 — New Standard, Specification for Failure Analysis Reporting
- Doc. 7381 — Revision to Add a New Subordinate Standard, Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125, Specification for Substrate Mapping

### 3.3.5 Authorized Activities

#### 3.3.5.1 7 SNARFS were approved.

- Doc. XXXX — Line Item Revision to SEMI E116-0324, Specification for Equipment Performance Tracking
- Doc. XXXX — Line Item Revision to SEMI E172-0725, Specification for SECS Equipment Data Dictionary (SEDD)
- Doc. XXXX — Revision to Add a New Subordinate Standard, Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services
- Doc. XXXX — Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224, Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1224 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224 Specification for Data Collection



Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components

- Doc. XXXX — Line Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
- Doc. XXXX — Line Item Revision to SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)
- Doc. XXXX — Line Item Revision to SEMI E190.1-1124 - Specification for Common Data for Etch Components

### 3.3.6 Authorized Ballots

3.3.7 1 Ballot was authorized to proceed in cycle 9, 2025.

- Doc. R6743C — Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment

3.3.8 13 Ballots were authorized to proceed in cycle 1, 2026.

- Doc. 6926A — New Standard, Specification for Equipment Operator Access Management and Monitoring
- Doc. 7231 — Revision to Add a New Subordinate Standard, Specification for Protocol Buffers for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting
- Doc. 7187 — Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
- Doc. 7344A — Line Item Revision to SEMI E192-0121 – Guide for Equipment Adoption Criteria for GEM and GEM-Related Standards
- Doc. 7345A — Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking
- Doc. 7380A — Line Item Revision to SEMI E142-0225 - Specification for Substrate Mapping, SEMI E142.1-0225 — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 (0225) — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 (0225) — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer
- Doc. XXXX — Line Item Revision to SEMI E116-0324, Specification for Equipment Performance Tracking
- Doc. XXXX — Line Item Revision to SEMI E172-0725, Specification for SECS Equipment Data Dictionary (SEDD)
- Doc. XXXX — Revision to Add a New Subordinate Standard, Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services
- Doc. XXXX — Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224, Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1224 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components
- Doc. XXXX — Line Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting



- Doc. XXXX — Line Item Revision to SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)
- Doc. XXXX — Line Item Revision to SEMI E190.1-1124 - Specification for Common Data for Etch Components

### 3.3.9 5-Year Review

3.3.10 SEMI E54. 11-0316 (Reapproved 0721) — Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices

3.3.11 SEMI E54.3-0698 (Reapproved 0721) — Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device

3.3.12 SEMI E173-0721 — Specification for XML SECS-II Message Notation (SMN)

3.3.13 Please find the attached file for details of TF activities.

**Attachment:** 6. NA IC Liaison Report 2025-10 - v3

## 3.4 I&C Taiwan TC Chapter

Natalie Shim (SEMI Korea) reported for the Taiwan TC Chapter. Of note:

### 3.4.1 Meeting Information

- Last Meeting: June 12, 2025 / OVTCCM
- Next Meeting: Date to be decided

### 3.4.2 Leadership Changes

#### 3.4.2.1 Equipment Edge Data Governance TF

- Ya Chi Tu (TSMC) was appointed as co-leader.

### 3.4.3 Ballot Results

- Doc. 6938C — New Standard, Guide for Equipment Edge Data Governance — **passed** with editorial changes, and will be forwarded to ISC A&R.

### 3.4.4 Authorized Activities

- TC Chapter approved Ya Chi Tu (TSMC) to be co-leader of Equipment Edge Data Governance TF.

### 3.4.5 SNARF(s) Abolished

- Doc. 7103 — Line Item Revision to SEMI E187(0122)- Specification for Cybersecurity of Fab Equipment

**Attachment:** 7. IC Taiwan Liaison Report\_20250612\_V1

## 3.5 SEMI Staff Report

Natalie Shim (SEMI Korea) gave the SEMI Staff Report. Of note:

### 3.5.1 SEMICON Upcoming Events

- SEMICON Japan: Dec 17-19, 2025, Tokyo
- SEMICON Korea: February 11-13, 2026, Seoul
- SEMICON China: March 25-27, 2026, Shanghai
- SEMICON Southeast Asia, May 5-7, 2026, Kuala Lumpur



### 3.5.2 Global Standards Summit (GSS) 2025

- The Second Global Standards Summit (GSS) was held on October 7, in conjunction with SEMICON WEST 2025. The summit has been aimed to identify standards-critical areas and work towards advancing an industry-wide standardization roadmap for the next 3- and 7-year horizons. This year's theme was "Future Standards for Connected & Sustainable Semiconductor Manufacturing", with a primary focus on supply chain traceability and environmental sustainability.

### 3.5.3 Workshops at SEMICON WEST 2025

- SEMI Liquid Chemicals Analytical Workshop was held on October 8.
- Enhancing Voltage Sag Immunity: SEMI F47 Standard Updates & Insights was held on October 8.
- Semiconductor Device Manufacturing in a Cleanroom (Best Practices to Improve Product Reliability and Yield) was held on October 9.

### 3.5.4 Upcoming NA Meetings 2026

#### 3.5.4.1 The schedule has been updated as follows:

- NA Winter Meetings on February 9 to 12 via full virtual meeting
- NA Spring Meeting on May 11 to 14 at Hilton Albany, New York, in conjunction with ASMC
- SEMICON West Meeting on October 12 to 15 at San Francisco

### 3.5.5 Critical Dates for SEMI Standards Ballots

- See <https://www.semi.org/en/Standards/Ballots>

### 3.5.6 SEMI Advanced Semiconductor Manufacturing Conference (ASMC)

3.5.7 ASMC 2026 will be held on May 11 to 14, 2026, at Hilton Albany, New York. It is SEMI's international technical conference for discussing solutions that improve the collective manufacturing expertise of the semiconductor industry. The conference will provide a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.

3.5.8 All SEMI Standards Task Forces shall use Connected@SEMI for managing TF activities and storing documents.

**Attachment:** 8. Staff\_HQ Report Nov 2025 v5

9. GSS2025 Planning Committee Meeting 2025Oct20 Audience+PostEvent\_Surveys

## 4 Ballot Review

None

## 5 Subcommittee and Task Force Reports

### 5.1 Diagnostic Data Acquisition (DDA) TF

5.1.1 Hyungsu Kim (Doople) gave a report on NA DDA TF meeting held on October 7, in conjunction with SEMICON WEST 2025.

### 5.2 Advanced Back-End Factory Integration (ABFI) TF

Youngshin Lim (Miracom) delivered a presentation on potential standardization items for back-end factories. The ABFI TF will continue detailed discussions on potential standardization items on January 29, 2026 via OVTCCM. Those who would like to join the discussion, please inform SEMI Korea of their interest in participating via email.



## 6 Old Business

None

## 7 New Business

None

## 8 Next Meeting and Adjournment

The next meeting is scheduled for Thursday, April 23, 2026, via OVTCCM. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 5:00 PM.

Respectfully submitted by:

Cindy Bae

Coordinator

SEMI Korea

Phone: 82.2.531.7899

Email: [sbae@semi.org](mailto:sbae@semi.org)

Minutes tentatively approved by:

Chul Hong Ahn (SK hynix), Co-chair	<Date approved>
Hyungsu Kim (Doople), Co-chair	<Date approved>
Kelvin Lee (Lam Research), Co-chair	<Date approved>

**Table 14 Index of Available Attachments<sup>#1</sup>**

<i>Title</i>	<i>Title</i>
1. Required Meeting Elements March 2024	6. NA IC Liaison Report 2025-10 - v3
2. Agenda_I&C TC_November27_2025	7. IC Taiwan Liaison Report_20250612_V1
3. I&C TC Meeting Minutes_July 18_2025_v2	8. Staff_HQ Report Nov 2025 v5
4. China I&C Committee Chapter Liaison Report - Nov. 2025 v1	9. GSS2025 Planning Committee Meeting 2025Oct20 Audience+PostEvent_Surveys
5. JA_I&C_Liaison_2025_Nov_rev1	

<sup>#1</sup> Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.